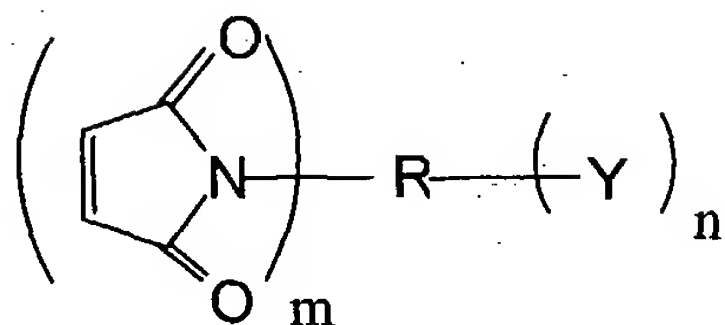
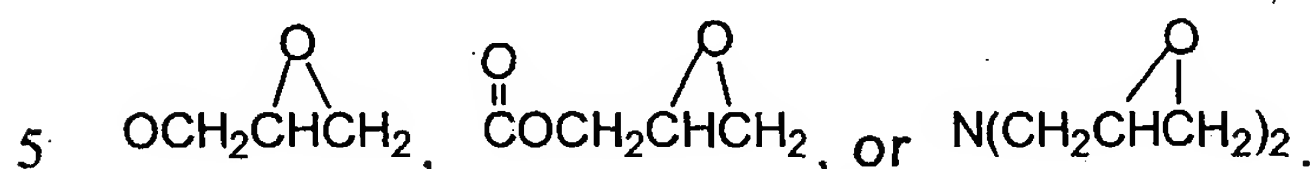


1. A compound having the following structure:



wherein m and n are integers not less than 1, R is a residue having at least one carbon and a valence equal to the sum of m and n, and Y is



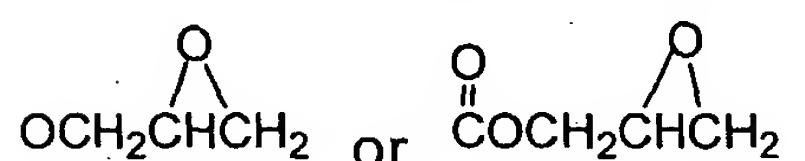
2. The compound as claimed in Claim 1, wherein R is an aromatic residue.

10 3. The compound as claimed in Claim 2, wherein R is a residue of benzene.

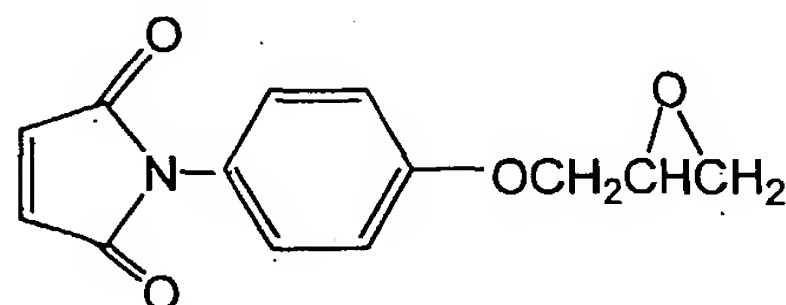
4. The compound as claimed in Claim 1, wherein m is 1, and n is 1 or 2.

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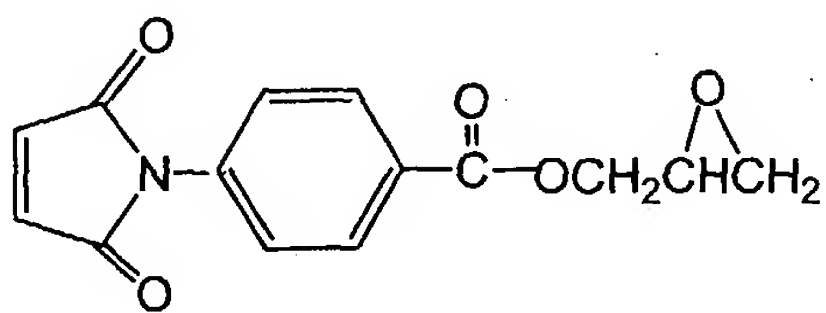
5. The compound as claimed in Claim 1, wherein Y is



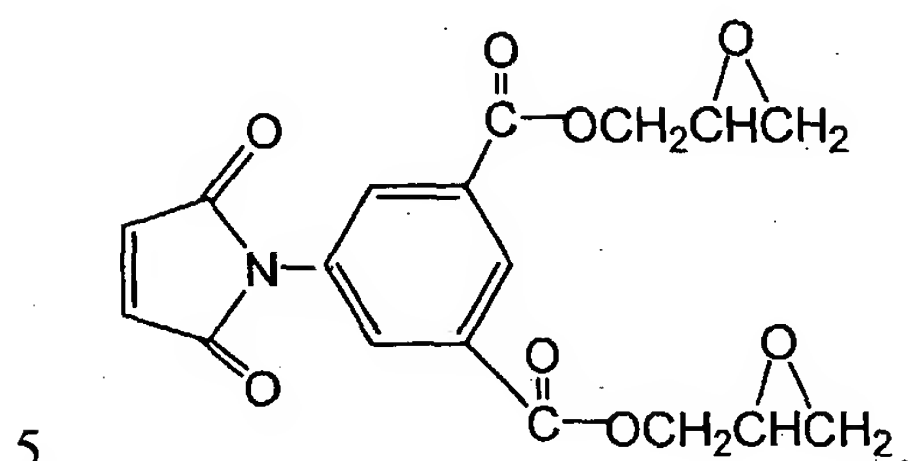
20 6. The compound as claimed in Claim 1 having the following structure:



7. The compound as claimed in Claim 1 having the following structure:



8. The compound as claimed in Claim 1 having the following structure:



9. A cured thermoset resin prepared by curing a compound as claimed in Claim 1.

10 10. A cured thermoset resin prepared by curing a compound as claimed in Claim 1 together with an additional compound or an additional resin.

11. The cured thermoset resin as claimed in Claim 9, wherein said
15 curing is carried out in the presence of a curing agent.

12. The cured thermoset resin as claimed in Claim 10, wherein said curing is carried out in the presence of a curing agent.

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